

Surface Mount General Purpose Silicon Rectifiers

Reverse Voltage - 50 to 1000 V

Forward Current - 3 A

FEATURES

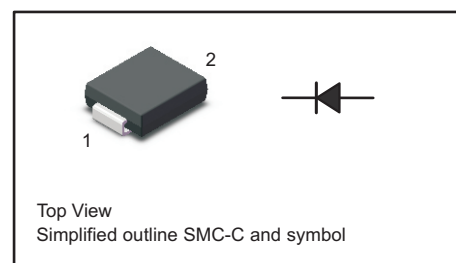
- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- Case: SMC-C
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.22g / 0.0077oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	S3AC	S3BC	S3DC	S3GC	S3JC	S3KC	S3MC	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	3							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	90							A
Maximum Instantaneous Forward Voltage at 3 A	V_F	1.0							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a = 25\text{ }^\circ\text{C}$							μA
		$T_a = 125\text{ }^\circ\text{C}$							
Typical Junction Capacitance ⁽¹⁾	C_j	24							pF
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$ $R_{\theta JC}$	75							$^\circ\text{C/W}$
		15							
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							$^\circ\text{C}$

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 0.2" X 0.2" (5 X 5 mm) copper pad areas.



Fig.1 Forward Current Derating Curve

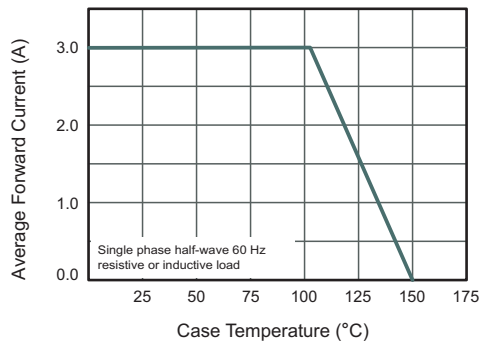


Fig.2 Typical Reverse Characteristics

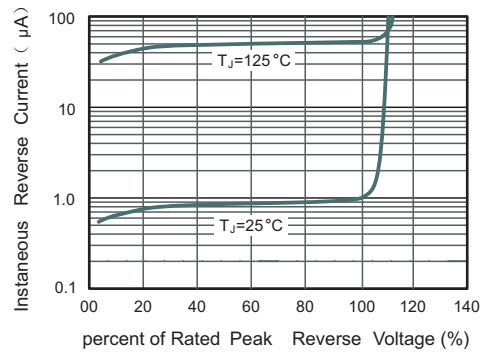


Fig.3 Typical Forward Characteristic

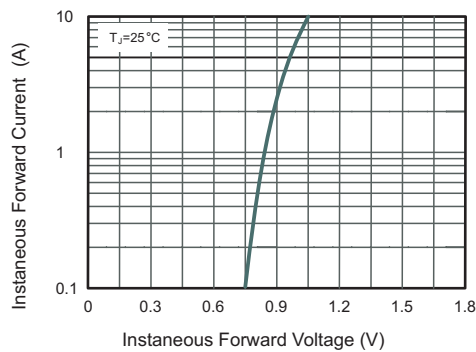


Fig.4 Typical Junction Capacitance

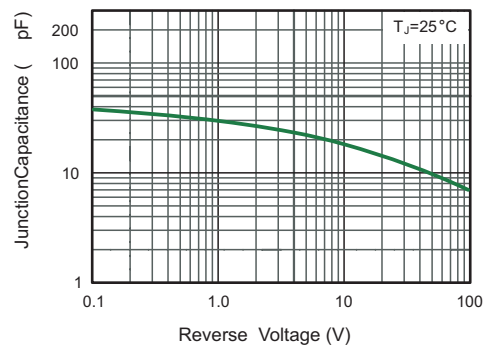
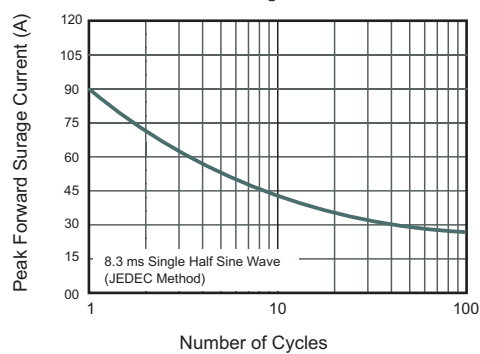


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current

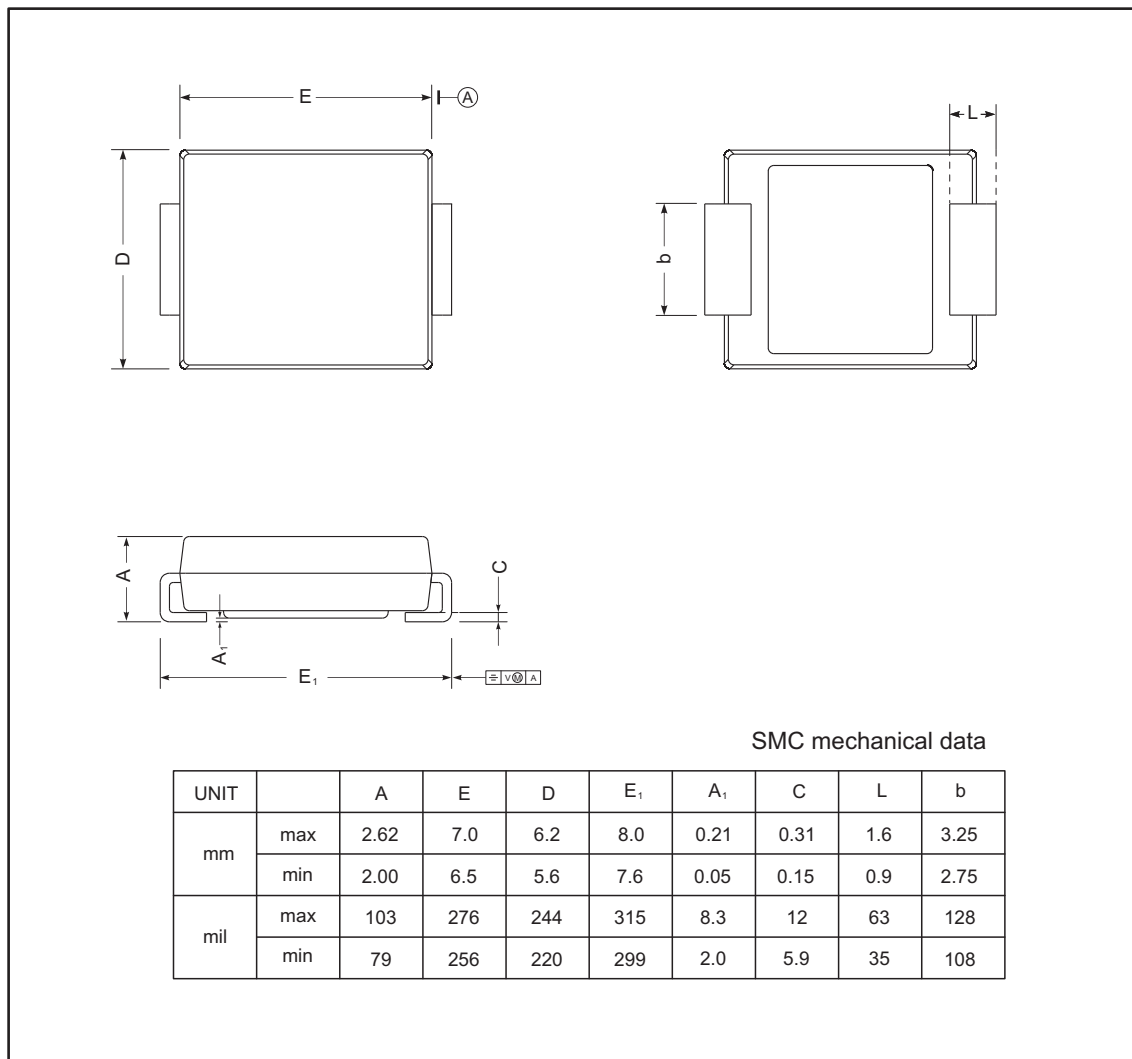




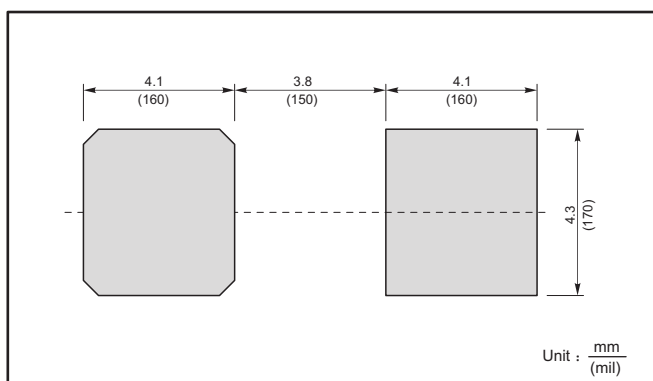
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMC-C



The recommended mounting pad size



Marking

Type number	Marking code
S3AC	S3A
S3BC	S3B
S3DC	S3D
S3GC	S3G
S3JC	S3J
S3KC	S3K
S3MC	S3M



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